TESIS UCH

FACULTAD DE CIENCIAS E INGENIERÍA
ESCUELA PROFESIONAL DE INGENIERÍA DE SISTEMAS E INFORMÁTICA

TRABAJO DE INVESTIGACIÓN PARA OBTENER EL GRADO ACADÉMICO DE BACHILLER EN INGENIERÍA DE SISTEMAS E INFORMÁTICA

A Mobile Application with Augmented Reality for the Learning of the Quechua Language in Pre-School Children

PRESENTADO POR

Zapata-Paulini, Joselyn Esther

Co-Autores

Soto-Cordova, Martín Moises
Lapa-Asto, Ulises Semilis

Los Olivos, 2020

Tesis publicada con autorización de los autores
no olvide citar esta tesis

www.uch.edu.pe

Proceeding Conference

A Mobile Application with Augmented Reality for the Learning of the Quechua Language in Pre-School Children

Joselyn Esther Zapata-Paulini[a], Martín Moises Soto-Cordova[a], Ulises Semilis Lapa-Asto[a]

[a] Universidad de Ciencia y Humanidades (UCH). Facultad de Ciencias e Ingeniería. Escuela Profesional de Ingeniería de Sistemas e Informática

ABSTRACT

In Peru, Quechua-speaking people decrease every year due to disinterest, discrimination, lack of motivation for language learning even more in educational centers, lack of teachers willing to teach the language and lack of teaching materials with which children can interact during His learning. Augmented Reality (AR) is a great ally of education providing efficiency, productivity and increasing the interest of students in their academic activities. This paper is structured and implemented an application with AR for the learning of Quechua in preschool children, which will give children the possibility to connect with their environment, their own history and their ancestors in a fun way, and grow with a different awareness of the others, in addition to providing linguistic stimuli achieving greater ease for learning other languages, since after mastering this language develops skills for new learning.

Keywords: mobile application, augmented reality, design thinking

Published in: 2019 IEEE 39th Central America and Panama Convention (CONCAPAN XXXIX)
Date of Conference: 20-22 Nov. 2019
Date Added to IEEE *Xplore*: 03 February 2020
ISBN Information:
Electronic ISBN:978-1-7281-0883-4
Print on Demand(PoD)
ISBN:978-1-7281-0884-1
INSPEC Accession Number: 19318971
DOI: 10.1109/CONCAPANXXXIX47272.2019.8976924
Publisher: Institute of Electrical and Electronics Engineers Inc. (IEEE)
Conference Location: Guatemala City, Guatemala, Guatemala